

## ABSTRACT OF THE DISCLOSURE

A conductive composition layer, conductive particles as a raw material, a conductive composition layer, etc. are provided wherewith heat conductance can be accelerated between electronic devices or electronic devices can be electrically connected. The conductive composition layer is formed by subjecting to heat treatment at a temperature lower than 230°C a conductive composition comprising conductive particles having a metal base material and a metal coating material thereon as well as a thermosetting resin having a curing temperature that is lower than 230°C and/or a thermoplastic resin having a melting point that is lower than 230°C.